

留学理由書  
STATEMENT OF PURPOSE

氏 名 Name	姓 Family name		名 Given names	
	KANKANAM MUDALIGE		THILINA SANDEEPA JAYAWICKRAMA	
生 年 月 日 Date of birth	2000/3/2 YYYY/MM/DD	国 籍 Nationality	スリランカ	性 別 Sex
				<input checked="" type="checkbox"/> 男 Male <input type="checkbox"/> 女 Female
現 住 所 Present address	63/A,INDALAWATHTHE,AYAGAMA ,SRI LANKA			

留学理由

Reason for studying Japanese.

I am Kankanam Mudalige Thilina Sandeepa Jayawickrama. I was born in 02/03/2000, so I am 23 years old now. I passed GCE O/L Examination in 2016 and In the year of 2019 I faced Advanced Level Examination in the field of Arts, because I was so interested in Media and I had a dream to become an announcer. After completion of my Advanced Level, I decided to join our family business because I felt I would need to earn money for my higher studies. Meanwhile, I had completed my Information Technology course from 12/10/2019 to 15/06/2020 at Don Bosco Technical Centre, Negombo. In that period, our business was somewhat developed, but I recognized we were spending more money than we were earning for our vehicle repairs. Due to high demand of motor mechanic, I decided to take motor mechanic course at State Ministry of Skills development, Vocational Education from 25/07/2020 to 12/06/2023. While I was taking the course, my interest in being a motor mechanic also increased day by day. After that I decided to migrate Japan to my higher studies of motor mechanism, the reason why I have chosen Japan as my dream destination is that Japan is the leading Asian country which is famous for vehicle industry as well as motor mechanism. My goal is to fly Japan as soon as possible to reach my target and expertise my Japanese Language skill level by entering the Japanese Language School. After that I hope to enter vocational school and after completion of Technical education I hope to work in a leading vehicle company in Japan to gain experience. My ambition is to start my own vehicle repairing center both in Japan and Sri Lanka.

申請日

2023 年 10 月 25 日

出願者署名



Date of application

YYYY

MM

DD

Signature of the applicant